



## 36 -- Inductively Coupled Plasma/Plasma Enhanced Chemical Vapor Deposition Process Gas Delivery and Abatement System

- [Synopsis](#) - Posted on Aug 11, 2005

### General Information

Document Type: Modification to a Previous Notice  
Solicitation Number: N00173-05-R-CR10  
Posted Date: Aug 26, 2005  
Original Response Date: Sep 07, 2005  
Current Response Date: Sep 07, 2005  
Original Archive Date: Aug 11, 2006  
Current Archive Date: Aug 11, 2006  
Classification Code: 36 -- Special industry machinery  
Set Aside: Total Small Business  
Naics Code: 325120 -- Industrial Gas Manufacturing

### Contracting Office Address

Department of the Navy, Office of Naval Research, Naval Research Laboratory, 4555 Overlook Ave. S.W., Washington, DC, 20375

### Description

The purpose of this amendment is to address potential offeror's questions.

Question 1: To ensure that the abatement system is sized appropriately to handle the process gases listed

in Table 2, should the offeror assume that the typical process gas flows for this application equal the Min Flow Rate (SCCM) stated in Table 2?

Answer to Question 1: Yes. The abatement system must be configured to handle the minimum gas flows listed in Table 2.

Question 2: In Section 7 it states, "The system is to be of passive dry chemical absorbance or gas reactor column design." Is NRL open to other effective abatement technologies for this application that will have a significantly lower Cost of Ownership compared to dry chemical absorbance abatement technology?

Answer to Question 2: Yes.

Question 3: Does the NRL facility have acid drain capabilities?

Answer to Question 2: Yes.

Question 4: How many chambers does the Oxford tool have?

Answer to Question 4: There is one chamber in the Oxford PECVD system.

Question 5: What is the substrate being used in the PECVD process? Is it Silicon? Is it Gallium Nitride?

Answer to Question 5: A variety of substrates will be used in the multi-user PECVD system, including silicon, gallium nitride, gallium arsenide, diamond, and glass.

Question 6: The minimum gas flows are indicated in the specification, but what are the process gas flows? Are they different from the minimum?

Answer to Question 6: The gas flows are dependent on the process being implemented and the abatement equipment should be sized to handle the minimum flows listed in Table 2.

Question 7: The gases are typically put into the tool using Mass Flow Controllers. What are the maximum flow rates of these controllers for the different gases being used in the process?

Answer to Question 7: Vendors supplying gas abatement equipment are required only to meet the minimum flow requirements listed in Table 2. The values listed are actually the maximum mass flow controller ratings for the corresponding gas.

## **Point of Contact**

Alan Crupi, Contract Specialist, Phone 202-767-3595, Fax 202-767-0430, Email wayne.crupi@nrl.navy.mil - F. Janilea Bays, Contracting Officer, Phone 202-767-2974, Fax 202-767-0430, Email jan.bays@nrl.navy.mil

## Place of Performance

Address: Naval Research Laboratory 4555 Overlook Ave SW Washington, DC  
Postal Code: 20375

[Register to Receive Notification](#)

---

### Government-wide Numbered Notes

#### **You may return to Business Opportunities at:**

- DON ONR listed by [\[Posted Date\]](#)
- DON Agencywide listed by [\[Posted Date\]](#)

---

[\[Home\]](#) [\[SEARCH synopses\]](#) [\[Procurement Reference Library\]](#)